Build Up HDI (Standard)

HDI06_1+4+1_0,85_17.5_engl

6 - Layers

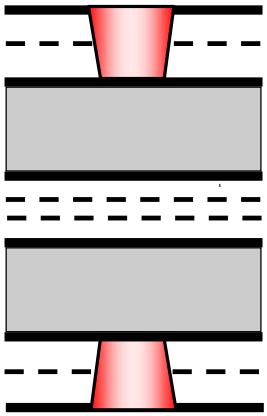
Core: 0,25 mm Cu 17/17 µm

WE-Artikel Nr.:

1 + 4 + 1

KUNDE:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	**66**	
	2			17,5 µm		**16**	
			0,250 mm			**250**	
	3			17,5 µm		**16**	
					2 x 1080	**134**	
	4			17,5 µm		**16**	
			0,250 mm			**250**	
	5			17,5 µm		**16**	
					1 x 1080	**66**	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 854

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**0,85**	+/-	0,06	mm			Date:	Engineer:
thickness with electro plated Cu:	0,94	+/-	0,09	mm				
total thickness with soldermask	1,00	+/-	0,11	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision		
05.01.2006	**S. Keller**	04.05.2006	M.Kress	05.01.2006	R. Schönholz	00	page:	8+